



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE42694-2EL			<b>Issued</b>	29. August 2013			
<b>MA#</b>	MA001024508							
<b>Package</b>	PG-SSOP-14-2			<b>Weight*</b>	82.84 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.353	1.63	1.63	16329	16329
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		416	
	non noble metal	iron	7439-89-6	0.689	0.83		8317	
wire	non noble metal	copper	7440-50-8	27.978	33.77	34.65	337721	346558
	noble metal	gold	7440-57-5	0.132	0.16	0.16	1599	1599
	encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1216
encapsulation	plastics	epoxy resin	-	4.633	5.59		55931	
	inorganic material	silicondioxide	60676-86-0	45.630	55.09	60.80	550799	607946
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11783	11783
plating	noble metal	silver	7440-22-4	0.768	0.93	0.93	9266	9266
glue	plastics	epoxy resin	-	0.135	0.16		1630	
	noble metal	silver	7440-22-4	0.405	0.49	0.65	4889	6519
*deviation	< 10%			Sum in total:		100,00		1000000

### Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com